

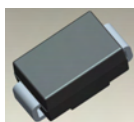
## 3.0A SURFACE MOUNT GLASS PASSIVATED RECTIFIER

### Features

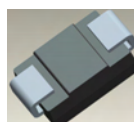
- Glass Passivated Die Construction
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 100A Peak
- Ideally Suited for Automated Assembly
- **Lead Free Finish/RoHS Compliant (Note 1)**
- **Green Molding Compound (No Halogen and Antimony) (Note 2)**
- **Qualified to AEC-Q101 Standards for High Reliability.**

### Mechanical Data

- Case: SMB/SMC
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 
- Polarity: Cathode Band or Cathode Notch
- Weight: SMB 0.093 grams (approximate)  
SMC 0.21 grams (approximate)



Top View



Bottom View

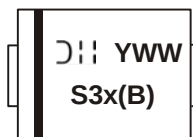
### Ordering Information\* (Note 3)

| Part Number | Qualification | Case | Packaging        |
|-------------|---------------|------|------------------|
| S3xB-13-F   | Commercial    | SMB  | 3000/Tape & Reel |
| S3x-13-F    | Commercial    | SMC  | 3000/Tape & Reel |
| S3MBQ-13-F  | Automotive    | SMC  | 3000/Tape & Reel |

\*x = Device type, e.g. S3AB-13-F (SMB package); S3A-13-F (SMC Package).

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
  2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
  3. For packaging details, go to our website at <http://www.diodes.com>.

### Marking Information



S3x = Product Type Marking Code, ex. S3K (SMC)  
 S3xB = Product Type Marking Code, ex. S3KB (SMB)  
 S3x = Manufacturers' code marking  
 YWW = Date code marking  
 Y = Last digit of year (ex: 2 for 2002)  
 WW = Week code (01 to 53)

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
 For capacitance load, derate current by 20%.

| Characteristic                                                                                      | Symbol              | S3<br>A/AB | S3<br>B/BB | S3<br>D/DB | S3<br>G/GB | S3<br>J/JB | S3<br>K/KB | S3<br>M/MB | Unit |
|-----------------------------------------------------------------------------------------------------|---------------------|------------|------------|------------|------------|------------|------------|------------|------|
| Peak Repetitive Reverse Voltage                                                                     | V <sub>RRM</sub>    | 50         | 100        | 200        | 400        | 600        | 800        | 1000       | V    |
| Working Peak Reverse Voltage                                                                        | V <sub>RWM</sub>    |            |            |            |            |            |            |            |      |
| DC Blocking Voltage                                                                                 | V <sub>R</sub>      |            |            |            |            |            |            |            |      |
| RMS Reverse Voltage                                                                                 | V <sub>R(RMS)</sub> | 30         | 70         | 140        | 280        | 420        | 560        | 700        | V    |
| Average Rectified Output Current @ T <sub>T</sub> = 75°C                                            | I <sub>O</sub>      | 3.0        |            |            |            |            |            |            | A    |
| Non-Repetitive Peak Forward Surge Current 8.3ms<br>Single Half Sine-Wave Superimposed on Rated Load | I <sub>FSM</sub>    | 100        |            |            |            |            |            |            | A    |

**Thermal Characteristics**

| Characteristic                                           | Symbol                            | Value       | Unit |
|----------------------------------------------------------|-----------------------------------|-------------|------|
| Typical Thermal Resistance Junction to Terminal (Note 4) | R <sub>θJT</sub>                  | 10          | °C/W |
| Operating and Storage Temperature Range                  | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 | °C   |

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

| Characteristic                                         | Symbol          | Value | Unit |
|--------------------------------------------------------|-----------------|-------|------|
| Forward Voltage @ I <sub>F</sub> = 3.0A                | V <sub>FM</sub> | 1.15  | V    |
| Peak Reverse Current @ T <sub>A</sub> = 25°C           | I <sub>RM</sub> | 10    | μA   |
| at Rated DC Blocking Voltage @ T <sub>A</sub> = 125 °C |                 | 250   |      |
| Typical Total Capacitance (Note 5)                     | C <sub>T</sub>  | 40    | pF   |

Notes: 4. Thermal resistance: Junction to Terminal, unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pad as heat sink.  
 5. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

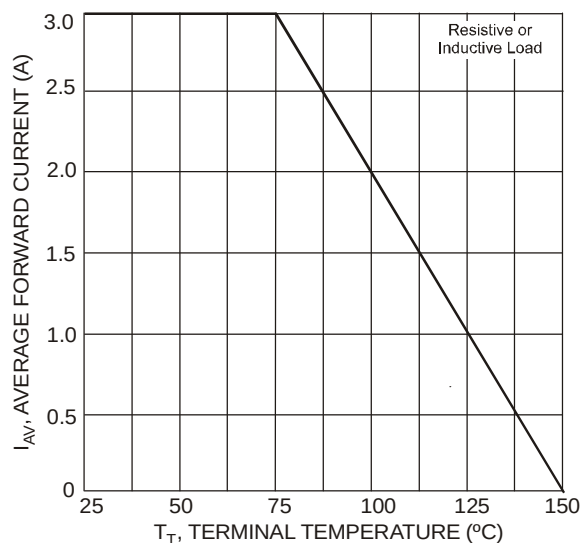


Fig. 1 Forward Current Derating Curve

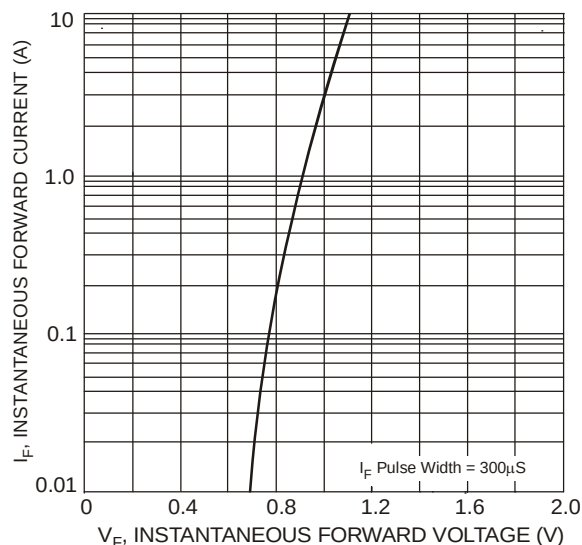


Fig. 2 Typical Forward Characteristics

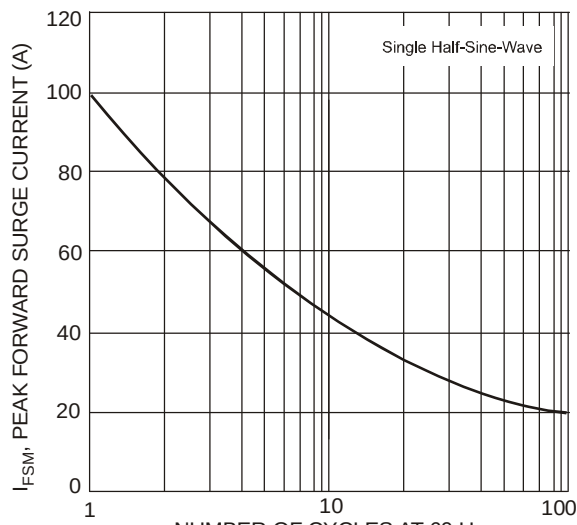


Fig. 3 Forward Surge Current Derating Curve

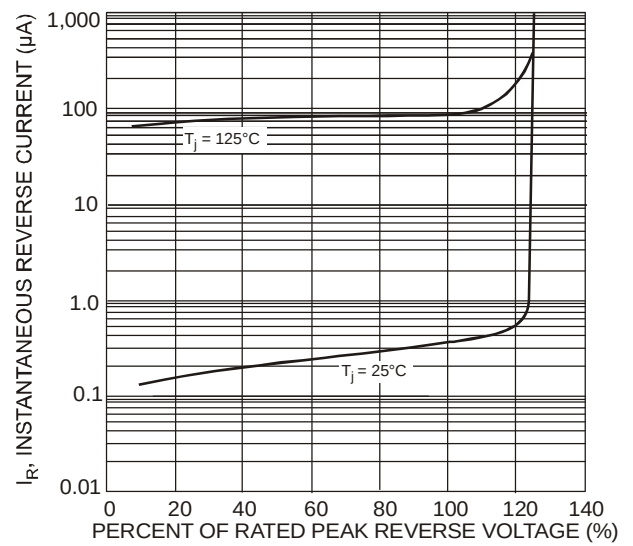
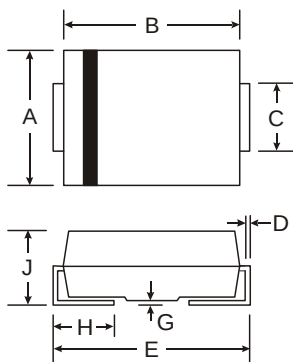


Fig. 4 Typical Reverse Characteristics

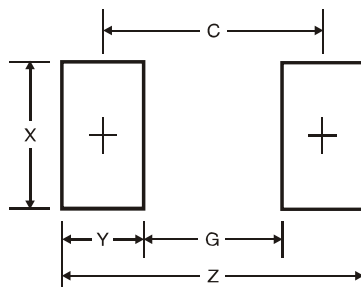
## Package Outline Dimensions



| SMB                  |      |      |
|----------------------|------|------|
| Dim                  | Min  | Max  |
| A                    | 3.30 | 3.94 |
| B                    | 4.06 | 4.57 |
| C                    | 1.96 | 2.21 |
| D                    | 0.15 | 0.31 |
| E                    | 5.00 | 5.59 |
| G                    | 0.05 | 0.20 |
| H                    | 0.76 | 1.52 |
| J                    | 2.00 | 2.50 |
| All Dimensions in mm |      |      |

| SMC                  |      |      |
|----------------------|------|------|
| Dim                  | Min  | Max  |
| A                    | 5.59 | 6.22 |
| B                    | 6.60 | 7.11 |
| C                    | 2.75 | 3.18 |
| D                    | 0.15 | 0.31 |
| E                    | 7.75 | 8.13 |
| G                    | 0.10 | 0.20 |
| H                    | 0.76 | 1.52 |
| J                    | 2.00 | 2.50 |
| All Dimensions in mm |      |      |

## Suggested Pad Layout



| SMB Dimensions | Value (in mm) |
|----------------|---------------|
| Z              | 6.7           |
| G              | 1.8           |
| X              | 2.3           |
| Y              | 2.5           |
| C              | 4.3           |

| SMC Dimensions | Value (in mm) |
|----------------|---------------|
| Z              | 9.3           |
| G              | 4.4           |
| X              | 3.3           |
| Y              | 2.5           |
| C              | 6.8           |

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